INTEGRATED CIRCUITS



Product specification IC15 Data Handbook

1989 Apr 06



Philips Semiconductors

74F1779

FEATURES

- Multiplexed 3-State I/O ports for bus oriented applications
- Built-in look-ahead carry capability
- Center power pins to reduce effects of package inductance
- Count frequency 145MHz typical
- Supply current 90mA typical
- See 74F269 for 24-pin separate I/O port version
- See 74F579 for 20-pin version
- See 74F779 for 16-pin version with abbreviated function table

DESCRIPTION

The 74F1779 is a fully synchronous 8-stage up/down counter with multiplexed 3-State I/O ports for bus-oriented applications. All control functions (hold, count up, count down, synchronous load) are controlled by two mode pins (S0, S1). The device also features carry look-ahead for easy cascading. All state changes are initiated by the rising edge of the clock. When CET is High, the data outputs are held in their current state and TC is held High. the TC output is not recommended for use as a clock or asynchronous reset due to the possibility of decoding spikes.

The 74F1779 differs from 74F779 in that it has an additional hold mode as described in the Function Table.

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

I/O1 [1	16 I/O0	
I/O2 2	15 CP	
I/O3 3	14 CET	
GND 4	13 V _{CC}	
I/O4 5	12 TC	
I/O5 6	11 S0	
I/O6 7	10 S1	
I/O7 8	9 OE	
'	l	SF01259

TYPE	TYPICAL f _{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F1779	130MHz	100mA

ORDERING INFORMATION

PIN CONFIGURATION

DESCRIPTION	$\begin{array}{l} \text{COMMERCIAL RANGE} \\ \text{V}_{\text{CC}} = 5\text{V}\pm10\%, \\ \text{T}_{\text{amb}} = 0^{\circ}\text{C to} +70^{\circ}\text{C} \end{array}$	PACKAGE DRAWING NUMBER	
16-pin Plastic DIP	N74F1779N	SOT38-4	
16-pin Plastic SOL	N74F1779D	SOT162-1	

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW	
l/On	Data inputs	3.5/1.0	70µA/0.6mA	
1/0/I	Data outputs	150/40	3.0mA/24mA	
S0, S1	Select inputs	1.0/1.0	20µA/0.6mA	
ŌĒ	Output Enable input (active Low)	1.0/1.0	20µA/0.6mA	
CET	Count Enable Trickle input (active Low)	1.0/1.0	20µA/0.6mA	
СР	Clock input (active rising edge)	1.0/1.0	20µA/0.6mA	
TC	Terminal Count output (active Low)	50/33	1.0mA/20mA	

NOTE: One (1.0) FAST unit load is defined as: 20μ A in the High state and 0.6mA in the Low state.

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LOGIC SYMBOL



IEC/IEEE SYMBOL



FUNCTION TABLE

	l	INPUTS	6							
S1	S0	CET	OE	СР						
Х	Х	Х	Н	Х	I/O0 to I/O7 in High impedance					
Х	Х	Х	L	Х	Flip-flop outputs appear on I/O lines					
L	L	Х	Н	\uparrow	Parallel load all flip-flops					
(not	LL)	Н	Х	\uparrow	Hold (TC held High)					
н	Н	Х	Х	\uparrow	Hold					
Н	L	L	Х	\uparrow	Count up					
L	Н	L	Х	\uparrow	Count down					

H = High voltage level L = Low voltage level X = Don't care ↑ = Low-to-High clock transition

(not LL) = S0 and S1 should never be Low voltage level at the same time in the hold mode only.

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LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS

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(Operation beyond the limits set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT	
V _{CC}	Supply voltage	-0.5 to +7.0	V	
V _{IN}	Input voltage	-0.5 to +7.0	V	
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in High output state	–0.5 to V_{CC}	V	
	Current applied to output in Low output atoto	TC	40	mA
OUT	Current applied to output in Low output state	I/On	48	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C	
T _{stg}	Storage temperature	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

SYMPOL	DADAMETED					
STWBOL	PARAMETER	MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	High-level input voltage					V
V _{IL}	Low-level input voltage				0.8	V
I _{IK}	Input clamp current				-18	mA
	High lovel output ourrest	TC			-1	mA
ЮН	nigh-level output current	l/On			-3	mA
		TC			20	mA
'OL	Low-level output current	I/On			24	mA
T _{amb}	Operating free-air temperature range		0		70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

	DADAMETED		TEST CONDITIONS			LIMITS				
STMBOL	PARAMETER	_				MIN TYP ² MAX		MAX		
		TO	$V_{CC} = MIN,$	1 1	±10%V _{CC}	2.5			V	
N			$V_{IH} = MIN$	$I_{OH} = -1 \text{ mA}$	±5%V _{CC}	2.7	3.4		V	
∨он	High-level output voltage	1/0-	$V_{CC} = MIN,$		±10%V _{CC}	2.4			V	
		1/On	$V_{IH} = MIN$	$I_{OH} = -3 \text{mA}$	±5%V _{CC}	2.7	3.3		V	
N			$V_{CC} = MIN,$	$V_{CC} = MIN,$			0.30	0.50	V	
VOL	Low-level output voltage		$V_{IH} = MIN$	$I_{OL} = MAX$	±5%V _{CC}		0.35	0.50	V	
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V	
1.	Input current at maximum	l/On	V _{CC} = 5.5V, \	$V_{\rm CC} = 5.5$ V, $V_{\rm I} = 5.5$ V				1	mA	
	input voltage	others	V _{CC} = 5.5V, V _I = 7.0V					100	μΑ	
I _{IH}	High-level input current	except	V _{CC} = MAX,	V _I = 2.7V				20	μΑ	
Ι _{ΙL}	Low-level input current	I/On	V _{CC} = MAX,	V _I = 0.5V				-0.6	mA	
I _{IH} +I _{OZH}	Off-state output current High-level voltage applied	1/07	V _{CC} = MAX,	V _O = 2.7V				70	μΑ	
I _{IL} +I _{OZL}	Off-state output current Low-level voltage applied	i/On	V _{CC} = MAX, V _O = 0.5V					-600	μΑ	
I _{OS}	Short-circuit output current ³		V _{CC} = MAX			-60		-150	mA	
		I _{ССН}					100	145	mA	
I _{CC}	Supply current (total)	I _{CCL}	V _{CC} = MAX				100	145	mA	
		I _{CCZ}					110	155	mA	

NOTES:

 For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
All typical values are at V_{CC} = 5V. T_{amb} = 25°C.
Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

	PARAMETER							
SYMBOL		TEST CONDITION	T _{ai} V ₍ C _L = 5	_{mb} = +25 _{CC} = +5.0 0pF, R _L =	°C IV = 500Ω	T _{amb} = 0°0 V _{CC} = +5. C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	Waveform 1	115	130		100		MHz
t _{PLH} t _{PHL}	Propagation delay CP to I/On	Waveform 1	4.0 5.0	6.5 7.0	10.0 10.5	4.0 5.0	10.5 11.0	ns
t _{PLH} t _{PHL}	Propagation delay CP to TC	Waveform 1	4.0 4.5	6.5 6.5	9.0 9.0	3.5 4.0	9.5 9.5	ns
t _{PLH} t _{PHL}	Propagation delay CET to TC	Waveform 2	2.0 2.5	4.0 4.5	6.5 7.0	2.0 2.5	7.5 7.5	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level	Waveform 4 Waveform 5	2.0 4.5	4.0 6.5	6.5 9.0	2.0 4.0	7.5 9.5	ns
t _{PHZ} t _{PLZ}	Output Enable time from High or Low level	Waveform 4 Waveform 5	1.0 1.0	3.0 4.0	6.0 7.0	1.0 1.0	6.5 7.5	ns

AC ELECTRICAL CHARACTERISTICS

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AC SETUP REQUIREMENTS

SYMBOL	PARAMETER	TEST CONDITION	$\begin{array}{l} {T_{amb}=+25^\circ C}\\ {V_{CC}=+5.0V}\\ {C_{L}=50pF}, {R_{L}=500\Omega} \end{array}$			T _{amb} = 0°C V _{CC} = +5. C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _s (H) t _s (L)	Setup time, High or Low I/O _n to CP	Waveform 3	4.0 3.5			4.5 3.5		ns
t _h (H) t _h (L)	Hold time, High or Low I/O _n to CP	Waveform 3	0 0			0 0		ns
t _s (H) t _s (L)	Setup time, High or Low CET to CP	Waveform 3	4.5 7.0			5.0 8.0		ns
t _h (H) t _h (L)	Hold time, High or Low CET to CP	Waveform 3	0 0			0 0		ns
t _s (H) t _s (L)	Setup time, High or Low Sn to CP	Waveform 3	7.5 8.5			8.0 9.5		ns
$t_{h}(H) \\ t_{h}(L)$	Hold time, High or Low Sn to CP	Waveform 3	0 0			0 0		ns
t _w (H) t _w (L)	CP Pulse width, High or Low	Waveform 1	3.0 4.5			3.0 5.5		ns

AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

The shaded areas indicate when the input is permitted to change for predictable output performance.







Waveform 2. Propagation Delay, CET Input to Terminal Count Output



Waveform 3. Data Setup and Hold Times







Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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TEST CIRCUIT AND WAVEFORMS





inches

0.17

0.020

0.13

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

0.068

0.051

0.021

0.015

0.049

0.033

0.014

0.009

OUTLINE VERSION		REFER	EUROPEAN			
	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT38-4						-92-11-17- 95-01-14

9

0.77

0.73

0.26

0.24

0.10

0.30

0.14

0.12

0.32

0.31

0.39

0.33

0.01

0.030

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SOT38-4

Product specification

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8-bit bidirectional binary counter (3-State)

SO16: plastic small outline package; 16 leads; body width 7.5 mm SOT162-1 А х = v (M) A H_E - 🛛 у Q (A₃ pin 1 index Ħ Ш Г 8 detail X ⊕ w M е bp 10 mm 0 5 scale DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	м max.	A ₁	A ₂	Α3	b _р	с	D ⁽¹⁾	E ⁽¹⁾	e	Η _E	L	Lp	Q	v	w	У	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT162-1	075E03	MS-013AA				-92-11-17 95-01-24	

Product specification

NOTES

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DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
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